Effective March 1998 Rev. 1-10-03

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and

	e named below) of the subject matter w					
Title: SUBSTRATE PROCESSING	METHOD AND APPARATUS					
, or	erial No, filed pplication No. , filed , and as amended o			amendments through		
I hereby state that I have reviewed an any amendment(s) referred to above.	d understand the content of the above-ide	ntified spe	ecification, including the	claims, as amended by		
defined in Title 37, Code of Federal I	o the Patent and Trademark Office all in Regulations, §1.56. Title 35, United States Code, §119 (and §					
	ted below and have also identified below					
COUNTRY	APPLICATION NO.	DA	TE OF FILING	PRIORITY CLAIMED		
Japan	2002-332944	No	vember 15, 2002	YES		
Japan	2002-334277	Nov	vember 18, 2002	YES		
I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application: APPLICATION SERIAL NO. U.S. FILING DATE STATUS: PATENTED, PENDING, ABANDONED						

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from <u>WATANABE & HOTTA</u> as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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The above application may be more particularly identified as	follows:
J.S. Application Serial No.	Filing Date November 14, 2003
Applicant Reference Number <u>GEB1984-US</u> Atty Docket N	To. <u>2003-1659A</u>
Fitle of Invention SUBSTRATE PROCESSING METHOD	AND APPARATUS